

**In the Claims:**

**Claim 1 (currently amended):** A structure comprising:

a laminate substrate having a top surface for receiving a semiconductor die;

an antenna element situated on said top surface of said laminate substrate, said antenna element coupled to a laminate substrate bond pad, said antenna element being coupled to said laminate substrate by a trace on said top surface of said laminate substrate;

a bonding wire providing an electrical connection between said laminate substrate bond pad and a semiconductor die bond pad.

**Claim 2 (canceled).**

**Claim 3 (original):** The structure of claim 1 wherein an input impedance of said antenna element matches an output impedance at said semiconductor die bond pad.

**Claim 4 (original):** The structure of claim 1 wherein said antenna element comprises copper.

**Claim 5 (withdrawn):** The structure of claim 1 wherein said antenna element comprises a square metal pad.

**Claim 6 (withdrawn):** The structure of claim 1 wherein said antenna element is selected from the group consisting of a slot line pattern, a meander line pattern, and a patch pattern.

**Claim 7 (withdrawn):** The structure of claim 1 wherein said laminate substrate comprises an organic laminate material.

**Claim 8 (withdrawn):** The structure of claim 1 wherein said laminate substrate comprises a ceramic laminate material.

**Claim 9 (withdrawn):** The structure of claim 1 further comprising a capacitor, said capacitor coupled to said antenna element.

**Claim 10 (withdrawn):** The structure of claim 9 wherein said capacitor is an embedded capacitor.

**Claim 11 (previously presented):** A structure comprising:  
a laminate substrate having a top surface;  
a first semiconductor die and a second semiconductor die attached to said top surface of said laminate substrate;

a first antenna element situated on said top surface of said laminate substrate, said first antenna element coupled to a first laminate substrate bond pad;

a second antenna element situated on said top surface of said laminate substrate, said second antenna element coupled to a second laminate substrate bond pad;

a first bonding wire providing an electrical connection between said first laminate substrate bond pad and a semiconductor die bond pad on said first semiconductor die;

a second bonding wire providing an electrical connection between said second laminate substrate bond pad and a semiconductor die bond pad on said second semiconductor die.

**Claim 12 (original):** The structure of claim 11 wherein said first antenna element is coupled to said first laminate substrate bond pad by a trace on said top surface of said laminate substrate.

**Claim 13 (original):** The structure of claim 11 wherein an input impedance of said first antenna element matches an output impedance at said semiconductor die bond pad on said first semiconductor die.

**Claim 14 (original):** The structure of claim 11 wherein said second antenna element is coupled to said second laminate substrate bond pad by a trace on said top surface of said laminate substrate.

**Claim 15 (original):** The structure of claim 11 wherein an input impedance of said second antenna element matches an output impedance at said semiconductor die bond pad on said second semiconductor die.

**Claim 16 (original):** The structure of claim 11 wherein said first antenna element comprises copper.

**Claim 17 (withdrawn):** The structure of claim 11 wherein said first antenna element is selected from the group consisting of a slot line pattern, a meander line pattern, and a patch pattern.

**Claim 18 (withdrawn):** The structure of claim 11 wherein said second antenna element is selected from the group consisting of a slot line pattern, a meander line pattern, and a patch pattern.

**Claim 19 (withdrawn):** The structure of claim 11 wherein said laminate substrate comprises an organic laminate material.

**Claim 20 (withdrawn):** The structure of claim 11 further comprising a capacitor, said capacitor coupled to said first antenna element.